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Form PTO-1449 (Modified)		Atty Docket No.: 003401.P001D1C1		Serial No.: 09/245,499			
List of Patents and Publications Statement (Use several sheets if necessary)			Applicant: Igor Y. Khandros				
Page 1 of 5			Filing Date: February 5, 1999				
REFERENCE DESIGNATION			U.S. PATENT DOCUMENTS				
Examiner Initials		Document No.		Class	Sub-Class	Filing date if appropriate	
KC	AA	5,414,298	Grube et al.	257	690	3/26/93	
	AB	5,442,282	Rostoker et al.	324	158.1	7/2/92	
	AC	5,495,667	Farnworth et al.	29	843	11/7/94	
	AD	5,189,507	Carlomagno et al.	257	777	6/7/91	
	AE	5,518,964	DiStefano et al.	437	209	7/7/94	
	AF	5,557,501	DiStefano et al.	361	704	11/18/94	
	AG	5,613,861	Smith	439	81	6/7/95	
	AH	5,007,576	Congleton et al.	228	103	12/26/89	
	AI	5,045,410	Hiesbock et al.	428	644	7/3/89	
	AJ	5,047,711	Smith et al.	324	158	8/23/89	
	AK	5,059,143	Grabbe	439	886	9/8/88	
FOREIGN PATENT DOCUMENTS							
No.		Document No.	Date	Country	Class	Sub-Class	Trans-lation
KC	AL	1003396	3/7/83	USSR	—	—	No
	AM	EP 0 708 338 A2	4/24/96	Europe	—	—	—
	AN	0 402 756 A2	12/19/90	Europe	—	—	—
	AO	0 593 966 A1	4/27/94	Europe	—	—	—
	AP	2 643 753	2/28/89	France	—	—	No
OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)							
KC	AR	Shih et al., "A Novel Elastomeric Connector for Packaging Interconnections, Testing and Burn-in Applications", IEEE Journal, May 21, 1995, pp. 126-133.					
KC	AS	Kong, et al., "Integrated electrostatically resonant scan tip for an atomic force microscope", J. Vac. Sci. Technol. B 11 (3), May/Jun 1993, pp. 634-641.					
KC	AT	"Compliant Lead Reform Tool and Process", IBM Technical Disclosure Bulletin, Vol. 31, No. 6, November 1988, pp. 160-162					
Examiner	Kandler		Date Considered 12/19/99				
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

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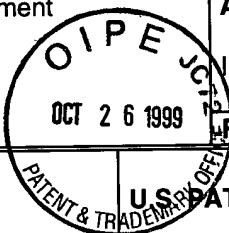
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Page 2 of 5			OCT 26 1999 Filing Date: February 5, 1999			
REFERENCE DESIGNATION		U.S. PATENT DOCUMENTS				
Examiner Initials		Document No.		Class	Sub-Class	Filing date if appropriate
KC	AA	5,066,907	Tarzwell et al.	324	158	2/6/90
	AB	5,095,187	Gliga	219	68	12/20/89
	AC	5,123,850	Elder et al.	439	67	6/7/91
	AD	5,136,367	Chiu	357	74	8/31/90
	AE	4,918,032	Jain et al.	437	228	7/8/88
	AF	4,998,885	Beaman	439	66	10/27/89
	AG	4,705,205	Allen et al.	228	180	5/14/84
	AH	4,724,383	Hart	324	158 F	5/3/85
	AI	4,732,313	Kobayashi et al.	228	179	7/26/85
	AJ	4,751,199	Phy	437	209	1/21/87
	AK	4,757,256	Whann et al.	324	158 P	5/1/87
FOREIGN PATENT DOCUMENTS						
No.		Document No.	Date	Country	Class	Sub-Class
Ke	AL	2 680 284	8/9/91	France	—	—
	AM	61287254	12/17/86	Japan (Abstract)	—	—
	AN	61244057	10/30/86	Japan (Abstract)	—	—
	AO	WO 96/02959	2/1/96	PCT	—	—
	AP	1 026 876	6/17/53	Germany	—	—
OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)						
Ke	AR	U. Renz, "Multipoint Test Probe for Printed Cards", IBM Technical Disclosure Bulletin, Vol. 17, No. 2, July 1974, pp. 2 pgs. total.				
Ke	AS	"Chip Column Package Structure", IBM Technical Disclosure Bulletin, Vol. 40, No. 08, August 1997, pp. 117-118.				
Ke	AT	Alan D. Knight, "MCM-TO-PRINTED WIRING BOARD (SECOND LEVEL) CONNECTION TECHNOLOGY OPTIONS", pp. 487-523. <u>No DATE</u>				
Examiner	Khandros		Date Considered	12/19/99		
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Page 3 of 5			Filing Date: February 5, 1999				
REFERENCE DESIGNATION		PATENT DOCUMENTS					
Examiner Initials		Document No.		Class	Sub-Class	Filing date if appropriate	
KL	AA	4,780,836	Miyazaki et al.	364	551.01	8/6/86	
	AB	4,634,199	Anhalt et al.	339-134	17-M69	1/22/85	
	AC	4,523,144	Okubo et al.	324	158 P	5/21/81	
	AD	4,553,192	Babuka et al.	361	395-743	8/25/83	
	AE	3,795,037	Luttmer	29	628	12/11/72	
	AF	5,350,947	Takekawa et al.	257	702	10/28/92	
	AG	4,667,219	Lee et al.	357-257	68-93	4/27/84	
	AH	5,067,007	Kanji et al.	357-257	74-701	1/24/91	
	AI	5,157,325	Murphy	324	158 F	2/15/91	
	AJ	5,218,292	Goto	324	158 F	12/9/91	
	AK	5,399,982	Driller et al.	324	754	5/4/93	
FOREIGN PATENT DOCUMENTS							
No.		Document No.	Date	Country	Class	Sub-Class	Trans-lation
KL	AL	3-142847 (A)	6/18/91	Japan	—	—	No
	AM	53-551134	9/5/78	Japan	—	—	No
	AN	56-26446 (A)	8/9/79	Japan	—	—	No
	AO	0 500 074 A1	2/19/92	Europe	—	—	—
	AP	0 614 089 A2	2/15/94	Europe	—	—	—
OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)							
KL	AR	Beaman et al., "ELASTOMERIC CONNECTOR FOR MCM AND TEST APPLICATIONS", ICEMM Proceedings '93, pp. 341-346.					
KL	AS	"Cooling System for Semiconductor Modules", IBM Technical Disclosure Bulletin, August 1983, pp. 2 pgs. total.					
KL	AT	"Method of Testing Chips and Joining Chips to Substrates", Research Disclosure, February 1991, No. 322, pp. 1.					
Examiner <i>Wm. Melvin</i>			Date Considered <i>12/19/99</i>				
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Page 4 of 5							
REFERENCE DESIGNATION		U.S. PATENT DOCUMENTS					
Examiner Initials		Document No.		Class	Sub-Class	Filing date if appropriate	
<i>KL</i>	AA	5,495,667	Farnworth et al.	29	843	11/7/94	
	AB	5,317,479	Pai et al.	361	773	10/1/93	
	AC	5,476,211	Khandros	228	180.5	11/16/93	
	AD	4,085,502	Ostman	29	629	4/12/77	
	AE	4,548,451	Benarr et al.	339-439	17-M85	4/27/84	
	AF	3,842,189	Southgate	174	52	1/8/73	
	AG	5,166,774	Banerji et al.	361	398	10/5/90	
	AH	5,097,100	Jackson	174	94 R	1/25/91	
	AI	5,071,359	Arnio et al.	439	91	4/27/90	
	AJ	2,869,040	Pifer	317	101	1/11/54	
<i>KL</i>	AK	5,109,596	Driller et al.	29	705	11/13/89	
FOREIGN PATENT DOCUMENTS							
No.		Document No.	Date	Country	Class	Sub-Class	Trans-lation
<i>KL</i>	AL	0 402 756 A2	06/06/90	Europe	—	—	—
<i>KL</i>	AM	WO 91/12706	8/22/91	PCT	—	—	—
<i>KL</i>	AN	61287254	12/17/86	Japan	—	—	No
	AO			<i>S</i>			
	AP						
OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)							
	AR						
	AS						
	AT						
Examiner <i>Khelen</i>		Date Considered <i>12/19/99</i>					
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Page 5 of 5		OCT 26 1999	Filing Date: February 5, 1999		
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Examiner Initials		Document No.		Class	Sub-Class
Ke		5,240,588	Uchida	205	125
		3,662,454	Miller	29	470.1
		4,707,657	Boegh-Petersen	324	158 F
		5,525,545	Grube et al.	437	209
		5,139,427	Boyd et al.	439	66
	▼	5,228,861	Grabbe	439	66
No.					
	AL				
	AM				
	AN				
	AO				
	AP				
OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)					
	AR				
	AS				
	AT				
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